1	L Number	Hits	Search Text	DB	Time stamp
1					
1   6618543.pn. and "650"   US-PGUB USPAT;   US-PGUB US		_			
1   6618543,pm, and "650"   USPAT;	2	1	6618543.pn. and "1.6"	USPAT;	2004/08/03 09:11
1	_			1	
1   6731856.pm.   USPAT; US-FGUB   EPO; JPO; DERWENT; IBM TOB   USPAT; US-FGUB   EPO; JPO; JPO; JPO; DERWENT; IBM TOB   USPAT; US-FGUB   EPO; JPO; JPO; DERWENT; IBM TOB   USPAT; US-FGUB   EPO; JPO; JPO; DERWENT; IBM TOB   USPAT; US-FGUB   EPO; JPO; JPO; DERWENT; IBM TOB   USPAT; US-FGUB   USPAT; US	3	1	6618543.pn. and "650"	4	2004/08/03 09:20
05   02   "04009807"   05   05   05   05   05   05   05   0			CT2105 C		0004400400
2	4	1	6/31856.pn.		2004/08/03 09:21
	5	. 2	"04009807"	4	2004/08/03 09:32
13		_	01003007		2004/00/03 09.32
Rurata.in. or Sharp.as.) and ((high adj transmitt\$6) or (absoprts6 adj coefficient) or wavequid33 or lightquid33) and (loake or baked or baking or cure or cured or curing or heat\$3 or harden\$3) with (polymer\$2 or polyimide or (poly adj imide) or resin\$3) with (vacuum or torr or (reduc\$3 adj pressure))				1	
transmit\$6) or (absorpt\$6 adj coefficient) or wavequid\$3 or lightpuid\$3 or (lawave or light) adj guid\$3)] and ((bake or baked or baking or cure or cured or curing or heat\$3 or harden\$3) with (polymer\$2 or polyimide or (poly) adj imide) or resin\$3) with (vacuum or torr or (reduc\$3 adj pressure)])  7	6	13	(Fujita.in. or Ishii.in. or Tamura.in. or	USPĀT;	2004/08/03 09:39
Or waveguid\$3 or lightquid\$3 or ((wave or light) adj guid\$3) and ((bake or baked or baking or cure or cured or curing or heat\$3 or harden\$3 with (polymer\$2 or polyimide or (poly adj imide) or resin\$3) with (vacuum or torr or (reduc\$3 adj pressure)))   7			• • • • • •	US-PGPUB;	
baking or cure or cured or curing or heat33 or harden33 with (vacuum or torr or (reduc\$3 adj pressure))				1	
heat33 or harden53) with (polymer52 or polyimide or (poly adj imide) or resins3) with (vacuum or torr or (reduc\$3 adj pressure))   (Fujita.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightquid\$3 or ((wave or light) adj guid\$3)) and ((bake or baked or baking or cure or cured or curing or heat\$3 or harden\$3) with (polymer\$2 or polyimide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) with (vacuum or torr or (reduc\$3 adj pressure)))   (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and ((high adj transmit\$6) or (pix) adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HD6100 or (hD adj "6100")) with (vacuum or torr or (reduc\$3 or lightquid\$3) or ((wave or light) adj guid\$3)) and ((bake or baked or baking or cure or cured or curing or heat\$3 or harden\$3 with (polymer\$2 or polyimide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) with (vacuum or torr or ((reduc\$3 or low\$3) near2 pressure)))   (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightquid\$3 or ((wave or light) adj guid\$3)) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))   (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightquid\$3 or ((wave or light) adj guid\$3)) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))   (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (Fux3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))   (Fujita.in. or Sharp.as.) and (Fux3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))   (SPAT; US-PGPUB, SPAT; US-PGPUB,				IBM_TDB	,
with (vacuum or torr or (reduc\$3 adj					
13					
Kurata.in. or Sharp.as.) and ((high adj transmits6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) and ((bake or baked or baked) or baking or cure or cured or curing or heat\$3 or harden\$3 with (polymer\$2 or polyimide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HB6100 or (fupidadj "6100")) with (vacuum or torr or (reduc\$3 adj pressure)))			pressure)))		
transmits6) or (absorpts6 adj coefficient) or waveguids3 or lightyuids3 or (wawe or light) adj guids3)) and (bake or baked or baking or cure or curring or heat\$3 or harden\$3) with (polymer\$2 or polyimide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) with (vacuum or torr or (reduc\$3 adj pressure)))  8	7	13			2004/08/03 09:40
				1	
Section   Sect					
Baking or cure or cureing or heat\$3 or harden\$3 with (polymer\$2 or polyimide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HB6100 or (HD adj "6100")) with (vacuum or torr or (reduc\$3 adj pressure)))					
heat\$3 or harden\$3) with (polymer\$2 or polymide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) with (vacuum or torr or (reduc\$3 adj pressure)))   Sample				TDM_IDB	
Polyimide or (poly adj imide) or resins3 or PIX3400 or (PIX adj "3400") or HD6100 or (reduc\$3 adj pressure)))					
Second Content of the Content of Content o					
0			or PIX3400 or (PIX adj "3400") or HD6100		
13			or (HD adj "6100")) with (vacuum or torr		
Rurata.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or (lightguid\$3) or (liwave or light) adj guid\$3)) and ((bake or baked or baking or cure or cured or curring or heat\$3 or harden\$3) with (polymer\$2 or polyimide or (poly adj imide) or resin\$3 or PIX\$400 or (PIX adj "3400") or Hb6100 or (HD adj "6100")) with (vacuum or torr or ((reduc\$3 or low\$3) near2 pressure))) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) adj guid\$3)) and (PIX\$400 or (PIX adj "3400") or Hb6100 or (HD adj "6100")) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (PIX\$400 or (PIX adj "3400") or Hb6100 or (HD adj "6100")) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (PIX\$400 or (PIX adj "3400") or Hb6100 or (HD adj "6100")) (PIX adj "3400") or Hb6100 or (HD adj "6100")) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (PIX\$400 or (PIX adj "3400") or Hb6100 or (HD adj "6100")) (PIX adj "3400") or Hb6100 or (HD adj "6100") (PIX a		1.0			
transmit\$6 or (absorpt\$6 adj coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) adj guid\$3)) and ((bake or baked or heat\$3 or harden\$3) with (polymer\$2 or polyimide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or Hb6100 or (Hb adj "6100")) with (vacuum or torr or ((reduc\$3 or lov\$3) near2 pressure)))   5	8	13		· ·	2004/08/03 09:41
or waveguid33 or lightguid\$3 or ((wave or light) add guid\$3)) and ((bake or baked or baking or cure or cured or curing or heat\$3 or harden\$3) with (polymer\$2 or polymide or (poly add imide) or resin\$3 or PIX3400 or (PIX add "3400") or HD6100 or (HD add) "6100")) with (wacuum or torror or ((reduc\$3 or low\$3) near2 pressure))) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and ((high add transmit\$6) or (absorpt\$6 add coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) add guid\$3)) and (PIX3400 or (PIX add) "3400") or HD6100 or (HD add) "6100")) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (PIX3400 or (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX add) "3400") or HD6100 or (HD add) "6100") (PIX					
			or waveguid\$3 or lightquid\$3 or ((wave or		
baking or cure or cured or curing or heat\$3 or harden\$3) with (polymer\$2 or polyimide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) with (vacuum or torr or ((reduc\$3 or low\$3) near2 pressure))) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) adj guid\$3)) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))  10					
Polyimide or (poly adj imide) or resin\$3 or PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) with (vacuum or torr or ((reduc\$3 or lox\$3) near2 pressure)))   Solid				_	
or PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) with (vacuum or torr or ((reduc\$3 or low\$3) near2 pressure)) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) adj guid\$3) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100")) (PIX adj "3400") or HD6100 or (HD adj "EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; (385/129,130,131,132,143)).CCLS.  11 3339 ((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS. USPAT; US-PGPUB USPAT					
9					
Or ((reduc\$3 or low\$3) near2 pressure))   Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) adj guid\$3)) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))   Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))   DERWENT; IBM_TDB   DERWE					
9					
Kurata.in. or Sharp.as.) and ((high adj transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) adj guid\$3)) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))	9	5		HCDAT.	2004/09/03 00.44
transmit\$6) or (absorpt\$6 adj coefficient) or waveguid\$3 or lightguid\$3 or ((wave or light) adj guid\$3)) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))  10		· ·			2004/00/03 09.44
or waveguid\$3 or lightguid\$3 or ((wave or light) adj guid\$3) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))  (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (PIX3400 or (HD adj "0100"))  (PIX adj "3400") or HD6100 or (HD adj "0100")  (PIX adj "3400") or HD6100 or (HD adj "0100")  (PIX adj "3400") or HD6100 or (HD adj "0100")  (A27/163.1,163.2) or (0100					
adj "3400") or HD6100 or (HD adj "6100"))  (Fujita.in. or Ishii.in. or Tamura.in. or Kurata.in. or Sharp.as.) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj EPO; JPO; DERWENT; IBM_TDB USPAT;  (385/129,130,131,132,143)).CCLS.  (427/372.2,379,385.5).CCLS.  (427/350).CCLS.  (528/310,322).CCLS.  ((427/163.1,163.2) or USPAT; US-PGPUB USPAT; US-PG			or waveguid\$3 or lightguid\$3 or ((wave or		
10			light) adj guid\$3)) and (PIX3400 or (PIX	IBM_TDB	
Kurata.in. or Sharp.as.) and (PIX3400 or (PIX adj "3400") or HD6100 or (HD adj "6100"))  11	110	_		HODAM	0004/00/00 15
(PIX adj "3400") or HD6100 or (HD adj "6100"))  11	1	5			2004/08/03 10:44
11   3339   ((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.   USPAT;   2004/08/03 10:44   USPAT;   USP					
11 3339 ((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.  12 344 (427/350).CCLS.  13 5209 (427/372.2,379,385.5).CCLS.  14 1745 (528/310,322).CCLS.  15 10528 (((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.) ((427/372.2,379,385.5).CCLS.) ((427/372.2,379,385.5).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) ((528/310,322).CCLS.) ((528/310,322).CCLS.) ((528/310,322).CCLS.) ((385/129,130,131,132,143)).CCLS.) and USPAT; US-PGPUB				1	
11 3339 ((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.  12 344 (427/350).CCLS.  13 5209 (427/372.2,379,385.5).CCLS.  14 1745 (528/310,322).CCLS.  15 10528 (((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/372.2,379,385.5).CCLS.) ((427/372.2,379,385.5).CCLS.) ((427/372.2,379,385.5).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) ((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((528/310,322).CCLS.) ((528/310,322).CCLS.) ((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) and USPAT; US-PGPUB					
12 344 (427/350).CCLS.  13 5209 (427/372.2,379,385.5).CCLS.  14 1745 (528/310,322).CCLS.  15 10528 (((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) ((528/310,322).CCLS.) ((528/310,322).CCLS.) ((528/310,322).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) ((385/129,130,131,132,143)).CCLS.) and USPAT; US-PGPUB	11	3339			2004/08/03 10:44
13 5209 (427/372.2,379,385.5).CCLS. US-PGPUB (427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) (427/372.2,379,385.5).CCLS.) (528/310,322).CCLS.) (528/310,322).CCLS.) (528/310,322).CCLS.) (16 0 (427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) and US-PGPUB US-PGPUB	12	~			
13 5209 (427/372.2,379,385.5).CCLS. USPAT; US-PGPUB USPAT; USPAT; US-PGPUB US-PGPUB USPAT; US-	12	344	(42//350).CCLS.		2004/08/03 10:45
14 1745 (528/310,322).CCLS. US-PGPUB USPAT; US-PGPUB US-PGPUB USPAT; US-PGPUB	13	5209	(427/372 2 379 385 5) CCTC	!	2004/09/02 10:45
14		5209	(\Left\\\)\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\		2004/08/03 10:45
15 10528 (((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) ((528/310,322).CCLS.) ((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) and US-PGPUB	14	1745	(528/310,322).CCLS.	l .	2004/08/03 10:45
(385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) (((427/163.1,163.2) or USPAT; US-PGPUB (385/129,130,131,132,143)).CCLS.) and US-PGPUB				· ·	,,,
((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) 16 0 ((427/163.1,163.2) or USPAT; 2004/08/03 10:45 (385/129,130,131,132,143)).CCLS.) and US-PGPUB	15	10528			2004/08/03 10:45
((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.) 16 0 ((427/163.1,163.2) or USPAT; USPAT; (385/129,130,131,132,143)).CCLS.) and US-PGPUB	ļ	;		US-PGPUB	
16 ((528/310,322).CCLS.) 0 ((427/163.1,163.2) or USPAT; 2004/08/03 10:45 (385/129,130,131,132,143)).CCLS.) and US-PGPUB					
16 0 (((427/163.1,163.2) or USPAT; USPAT; US-PGPUB 2004/08/03 10:45					
(385/129,130,131,132,143)).CCLS.) and US-PGPUB	16	ا م		поруд.	2004/08/03 10:45
((427/350).CCLS.)		Ĭ	(385/129,130,131,132,143)).CCLS.) and		2004/00/03 10:45
			((427/350).CCLS.)	22 232 32	

17	49	(((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) and	USPAT; US-PGPUB	2004/08/03 10:49
18	2	((427/372.2,379,385.5).CCLS.) (((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) and	USPAT; US-PGPUB	2004/08/03 10:50
19	12	((528/310,322).CCLS.) ((427/372.2,379,385.5).CCLS.) and ((528/310,322).CCLS.)	USPAT; US-PGPUB	2004/08/03 10:51
20	0	((427/350).CCLS.) and ((528/310,322).CCLS.)	USPAT; US-PGPUB	2004/08/03 10:59
21	47	((427/350).CCLS.) and	USPAT;	2004/08/03 11:00
22	441	((427/372.2,379,385.5).CCLS.) (((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) and	US-PGPUB USPAT; US-PGPUB	2004/08/03 11:01
23	23	(polyimide or (poly adj imide)) ((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.)	USPAT; US-PGPUB	2004/08/03 12:42
		((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.)	OB TOTOE	
		((528/310,322).CCLS.)) and (waveguid\$3 or (wave adj quid\$3) or lightquid\$3 or (light		
		adj guid\$3)) and (polyimide or (poly adj imide)) and ((heat\$3 or bake or baked or		
		baking or oven or cure or cured or curing or dry\$3 or harden\$3) with (polymer\$2 or		
		resin\$3 or polyimide or (poly adj imide) or core) with (vacuum or torr or pascal or		
		Pa or ((low\$4 or below\$4 or reduc\$5) near2		
24	130	pressure))) (waveguid\$3 or (wave adj guid\$3) or	USPAT;	2004/08/03 11:35
		lightguid\$3 or (light adj guid\$3)) and (polyimide or (poly adj imide)) and	US-PGPUB	
		((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3		
		or harden\$3) with (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core)		
		<pre>with (vacuum or torr or pascal or Pa or   ((low\$4 or below\$4 or reduc\$5) near2 pressure)))</pre>		
25	107	((waveguid\$3 or (wave adj guid\$3) or lightguid\$3 or (light adj guid\$3)) and	USPAT; US-PGPUB	2004/08/03 11:15
		(polyimide or (poly adj imide)) and ((heat\$3 or bake or baked or baking or	32 232 02	
		oven or cure or cured or curing or dry\$3		
		or harden\$3) with (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core)		
	:	with (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2		
		pressure)))) not (((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.)		
		((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.)		
		((528/310,322).CCLS.)) and (waveguid\$3 or (wave adj guid\$3) or lightguid\$3 or (light		
		adj guid\$3)) and (polyimide or (poly adj imide)) and ((heat\$3 or bake or baked or		
		baking or oven or cure or cured or curing or dry\$3 or harden\$3) with (polymer\$2 or		
		resin\$3 or polyimide or (poly adj imide) or core) with (vacuum or torr or pascal or		
		Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure))))		
26	6	waveguid\$3 or (wave adj guid\$3) or   lightquid\$3 or (light adj guid\$3)) and	EPO; JPO; DERWENT;	2004/08/03 11:37
		(polyimide or (poly adj imide)) and	IBM_TDB	
		((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3		
		or harden\$3) with (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core)		
		with (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2		
		pressure)))		

27	182	(polyimide or (poly adj imide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 11:45
28	180	( (polyimide or (poly adj imide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure))) not ((waveguid\$3 or (wave adj guid\$3) or lightguid\$3 or (light adj guid\$3)) and (polyimide or (poly adj imide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) with (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) with (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure))))	EPO; JPO; DERWENT; IBM_TDB	2004/08/03 11:38
29	32	Hitachi.as. and (polyimide or (poly adj imide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))	USPAT; US-PGPUB	2004/08/03 11:54
30	2	"02089059"	EPO; JPO; DERWENT; IBM TDB	2004/08/03 11:49
31	192	((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polyimide or (poly adj imide)) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)) with (coat\$3 or film or layer or deposit\$3 or core or apply\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 14:21
32	120	(((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polyimide or (poly adjimide)) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)) with (coat\$3 or film or layer or deposit\$3 or core or apply\$3))) not ((polyimide or (poly adjimide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polymer\$2 or resin\$3 or polyimide or (poly adjimide) or core) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))) not ((waveguid\$3 or (wave adjguid\$3) or lightguid\$3 or (light adjguid\$3)) and (polyimide or (poly adjimide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) with (polymer\$2 or resin\$3 or polyimide or (poly adjimide) or core) with (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 11:57

33	4	((((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03	11.57
		oven or cure or cured or curing or dry\$3	US-PGPUB;	2004/00/03	11:57
		or harden\$3) near6 (polyimide or (poly adj	EPO; JPO;		
		imide)) near7 (vacuum or torr or pascal or	DERWENT;		
		Pa or ((low\$4 or below\$4 or reduc\$5) near2	IBM TDB		
		pressure)) with (coat\$3 or film or layer	15.1_155		
		or deposit\$3 or core or apply\$3))) not ((			
		(polyimide or (poly adj imide)) and			
		((heat\$3 or bake or baked or baking or			
		oven or cure or cured or curing or dry\$3			
		or harden\$3) near6 (polymer\$2 or resin\$3			
		or polyimide or (poly adj imide) or core)			
		near7 (vacuum or torr or pascal or Pa or			
-		((low\$4 or below\$4 or reduc\$5) near2			
		pressure)))) not ((waveguid\$3 or (wave adj			
		guid\$3) or lightguid\$3 or (light adj			
		guid\$3)) and (polyimide or (poly adj			
		imide)) and ((heat\$3 or bake or baked or			
		baking or oven or cure or cured or curing			
		or dry\$3 or harden\$3) with (polymer\$2 or			
		resin\$3 or polyimide or (poly adj imide)			
		or core) with (vacuum or torr or pascal or			
		Pa or ((low\$4 or below\$4 or reduc\$5) near2			
		pressure)))))) and ((((427/163.1,163.2) or			
		(385/129,130,131,132,143)).CCLS.)			
		((427/350).CCLS.)			
		((427/372.2,379,385.5).CCLS.)			
L		((528/310,322).CCLS.))			

	r	F	T'	
34	116	((((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polyimide or (poly adjimide)) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)) with (coat\$3 or film or layer or deposit\$3 or core or apply\$3))) not ((polyimide or (poly adjimide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polymer\$2 or resin\$3 or polyimide or (poly adjimide) or core) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))) not ((waveguid\$3 or (wave adjguid\$3)) and (polyimide or (poly adjimide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) with (polymer\$2 or resin\$3 or polyimide or (poly adjimide) or core) with (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))))) not ((((heat\$3 or bake or baked or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) with (polymer\$2 or resin\$3 or polyimide or (poly adjimide) or core) with (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))))) not ((((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polyimide or (poly adjimide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polymer\$2 or resin\$3 or polyimide or (poly adjimide) or core) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure))))) not ((waveguid\$3 or harden\$3) not ((waveguid\$3 or harden\$3) or lightguid\$3 or (light adj guid\$3)) and (polyimide or (poly adjimide)) and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 12:20
35	1	<pre>(poly adj imide) or core) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))) not ((waveguid\$3 or (wave adj guid\$3) or lightguid\$3 or (light adj guid\$3)) and</pre>	USPAT; US-PGPUB; EPO; JPO;	2004/08/03 12:21
36	0	5310862.pn. and (tertiary adj amine)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/03 12:21

Page 5

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37	3	((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.)) and (waveguid\$3 or (wave adj guid\$3) or lightguid\$3 or (light adj guid\$3)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near5 (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) near5 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)) with (coat\$3 or film or layer or deposit\$3 or apply\$3 or spincoat\$3 or core or waveguid\$4 or lightguid\$4 or guid\$4)) ((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.)) and (waveguid\$3 or	USPAT; US-PGPUB	2004/08/03 12:44
		(wave adj guid\$3) or lightguid\$3 or (light adj guid\$3)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near5 (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) near5 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)) with (coat\$3 or film or layer or deposit\$3 or apply\$3 or spincoat\$3 or core or waveguid\$4 or lightguid\$4 or guid\$4))) not ((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.)) and (waveguid\$3 or (wave adj guid\$3) or lightguid\$3 or (light		
20		adj guid\$3)) and (polyimide or (poly adj imide)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) with (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) with (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure))))		
39	71	(waveguid\$3 or (wave adj guid\$3) or lightguid\$3 or (light adj guid\$3)) and ((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) near6 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)) with (coat\$3 or film or layer or deposit\$3 or apply\$3 or spincoat\$3 or core or waveguid\$4 or lightguid\$4 or guid\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 12:57

40	65	((waveguid\$3 or (wave adj guid\$3) or	USPAT;	2004/08/03 12:46
10,		lightguid\$3 or (light adj guid\$3)) and	US-PGPUB;	
		((heat\$3 or bake or baked or baking or	EPO; JPO;	
		oven or cure or cured or curing or dry\$3	DERWENT;	
			1	
		or harden\$3) near6 (polymer\$2 or resin\$3	IBM_TDB	
		or polyimide or (poly adj imide) or core)		1
		near6 (vacuum or torr or pascal or Pa or		
		((low\$4 or below\$4 or reduc\$5) near2		
		pressure)) with (coat\$3 or film or layer		
		or deposit\$3 or apply\$3 or spincoat\$3 or		
		core or waveguid\$4 or lightguid\$4 or		
		guid\$4))) not (((((427/163.1,163.2) or		
		(385/129,130,131,132,143)).CCLS.)		
		((427/350).CCLS.)		
		((427/372.2,379,385.5).CCLS.)		
		((528/310,322).CCLS.)) and (waveguid\$3 or		
		(wave adj guid\$3) or lightguid\$3 or (light		
		adj guid\$3)) and (polyimide or (poly adj		
		imide)) and ((heat\$3 or bake or baked or		
		baking or oven or cure or cured or curing		
		or dry\$3 or harden\$3) with (polymer\$2 or		
		resin\$3 or polyimide or (poly adj imide)		
		or core) with (vacuum or torr or pascal or		
		Pa or ((low\$4 or below\$4 or reduc\$5) near2		
		pressure))))		
41	283	((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 13:03
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
	1	or harden\$3) near6 (polymer\$2 or resin\$3	EPO; JPO;	
		or polyimide or (poly adj imide) or core)	DERWENT;	
		near6 (vacuum or torr or pascal or Pa or		
		· •	IBM_TDB	
		((low\$4 or below\$4 or reduc\$5) near2		
		pressure)) with (coat\$3 or film or layer		
		or deposit\$3 or apply\$3 or spincoat\$3 or		
		core or waveguid\$4 or lightguid\$4 or		
		guid\$4)) same (transparen\$5 or absorb\$8 or		
		absorp\$8 or (optical\$2 near2 (attenuat\$4		
		or loss)))		
42	5	( ((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 13:00
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) near6 (polymer\$2 or resin\$3	EPO; JPO;	
		or polyimide or (poly adj imide) or core)	DERWENT;	
		near6 (vacuum or torr or pascal or Pa or	IBM_TDB	
		((low\$4 or below\$4 or reduc\$5) near2		
		pressure)) with (coat\$3 or film or layer		
		or deposit\$3 or apply\$3 or spincoat\$3 or		
		core or waveguid\$4 or lightguid\$4 or		
		guid\$4)) same (transparen\$5 or absorb\$8 or		
		absorp\$8 or (optical\$2 near2 (attenuat\$4		
		or loss)))) and ((((427/163.1,163.2) or		
		(385/129,130,131,132,143)).CCLS.)		
		((427/350).CCLS.)		
		((427/372.2,379,385.5).CCLS.)		1
		((528/310,322).CCLS.))		
	i	[ ((250) 210, 255) (CDD-1)	i	1

43	072			
43	278	( ((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 13:03
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) near6 (polymer\$2 or resin\$3	EPO; JPO;	
'		or polyimide or (poly adj imide) or core)	DERWENT;	
		near6 (vacuum or torr or pascal or Pa or	IBM_TDB	
		((low\$4 or below\$4 or reduc\$5) near2		
		pressure)) with (coat\$3 or film or layer		
		or deposit\$3 or apply\$3 or spincoat\$3 or		
		core or waveguid\$4 or lightguid\$4 or		
		guid\$4)) same (transparen\$5 or absorb\$8 or		
		absorp\$8 or (optical\$2 near2 (attenuat\$4		
		or loss)))) not (( ((heat\$3 or bake or		
		baked or baking or oven or cure or cured		
	!	or curing or dry\$3 or harden\$3) near6		
		(polymer\$2 or resin\$3 or polyimide or		
		(poly adj imide) or core) near6 (vacuum or		
		torr or pascal or Pa or ((low\$4 or below\$4		į
		or reduc\$5) near2 pressure)) with (coat\$3		
		or film or layer or deposit\$3 or apply\$3		
	]	or spincoat\$3 or core or waveguid\$4 or		1
		lightguid\$4 or guid\$4)) same (transparen\$5	[	
		or absorb\$8 or absorp\$8 or (optical\$2		
		near2 (attenuat\$4 or loss)))) and		1
		((((427/163.1,163.2) or		
		(385/129,130,131,132,143)).CCLS.)	1	
		((427/350).CCLS.)		
		((427/372.2,379,385.5).CCLS.)		
44	0	((528/310,322).CCLS.)))	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	0004/00/00
**		(((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 13:04
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) near6 (polymer\$2 or resin\$3	EPO; JPO;	
		or polyimide or (poly adj imide) or core)	DERWENT;	
		near6 (vacuum or torr or pascal or Pa or	IBM_TDB	
		((low\$4 or below\$4 or reduc\$5) near2		
		pressure)) with (coat\$3 or film or layer		
		or deposit\$3 or apply\$3 or spincoat\$3 or		
		core or waveguid\$4 or lightguid\$4 or		
	1	<pre>guid\$4)) with (prevent\$4 near5 oxidiz\$6))</pre>		
	_	and (polyimide or (poly adj imide))		
45	5	(((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 13:05
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) near6 (polymer\$2 or resin\$3	EPO; JPO;	
		or polyimide or (poly adj imide) or core)	DERWENT;	
	i i	near6 (vacuum or torr or pascal or Pa or	IBM TDB	
	1	((low\$4 or below\$4 or reduc\$5) near2		
	1	pressure)) with (coat\$3 or film or laver		l i
	1	or deposit\$3 or apply\$3 or spincoat\$3 or		
		core or waveguid\$4 or lightquid\$4 or		
		guid\$4)) with (oxidiz\$6)) and (polyimide		
	]	or (poly adj imide))		ļ
46	10	(((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 13:07
		oven or cure or cured or curing or dry\$3	US-PGPUB;	2004/00/03 13:07
		or harden\$3) near6 (polymer\$2 or resin\$3	EPO; JPO;	İ
		or polyimide or (poly adj imide) or core)	DERWENT;	
		near6 (vacuum or torr or pascal or Pa or	IBM TDB	
		((low\$4 or below\$4 or reduc\$5) near2	מחו"ווחד	
		pressure)) with (coat\$3 or film or layer		
		or deposit\$3 or apply\$3 or spincoat\$3 or		
		core or waveguid\$4 or lightguid\$4 or		İ
		guid\$4)) with (oxidiz\$6 or oxidation)) and		
		(polyimide or (poly adj imide))		
		(borlarurge or (borla gg] imige))		

	<del></del>			
47	7	(((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3 or harden\$3) near6 (polymer\$2 or resin\$3 or polyimide or (poly adj imide) or core) near6 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)) with (coat\$3 or film or layer or deposit\$3 or apply\$3 or spincoat\$3 or core or waveguid\$4 or lightguid\$4 or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 13:24
49	2	<pre>guid\$4)) with (preferab\$5 or advantag\$6 or desir\$6)) and (polyimide or (poly adj imide)) (((((427/163.1,163.2) or</pre>	USPAT;	2004/08/03 13:26
		(385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.)) and (photosensit\$5 near3 (polyimide or (poly adj imide))) and waveguide) and \$8acetophenone and (tertiary adj amine)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
48	29		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 13:33
50	2		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 13:26
51	2	(HD6100 or (HD adj "6100"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/03 15:30
52	3	((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.)) and (photosensit\$5 near3 (polyimide or (poly adj imide))) and waveguide and \$8acetophenone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 13:28
53	10	(photosensit\$5 near3 (polyimide or (poly adj imide))) and waveguide and \$8acetophenone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/03 13:33
54	7	((photosensit\$5 near3 (polyimide or (poly adj imide))) and waveguide and \$8acetophenone) not ((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.) ((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.)) and (photosensit\$5 near3 (polyimide or (poly adj imide))) and waveguide and \$8acetophenone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 13:29
55	3597	((polyimide or (poly adj imide))) and waveguide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/03 13:33
56	120	(photosensit\$5 near3 (polyimide or (poly adj imide))) and waveguide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/03 13:33

57	91	((photosensit\$5 near3 (polyimide or (poly adj imide))) and waveguide ) not (((((427/163.1,163.2) or	USPAT; US-PGPUB; EPO; JPO;	2004/08/03 13:35
		((((427/163.1,163.2) 61 (385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.)	DERWENT; IBM TDB	
		((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.)) and (photosensit\$5		
		near3 (polyimide or (poly adj imide))) and waveguide)		
58	8		USPAT;	2004/08/03 14:21
	ļ	(((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.)	US-PGPUB; EPO; JPO;	
		((427/350).CCLS.)	DERWENT; IBM_TDB	
		((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.)) and (photosensit\$5		
		near3 (polyimide or (poly adj imide))) and waveguide)) and (((tertiary or tetra\$4)	ĺ	
59	9	( ( Danie of Danie of Danie of	USPAT;	2004/08/03 14:26
		oven or cure or cured or curing or dry\$3 or harden\$3) with (polyimide or (poly adj	US-PGPUB; EPO; JPO;	
		imide) or polymer\$2 or resin\$5) near7 (vacuum or torr or pascal or Pa or ((low\$4	DERWENT; IBM_TDB	
		or below\$4 or reduc\$5) near2 pressure)) with (coat\$3 or film or layer or deposit\$3		
		or core or apply\$3)) same ((pressure near5 (depend\$5 or advantag\$8 or benefi\$7 or		
60	47	1	USPAT;	2004/08/03 14:50
		oven or cure or cured or curing or dry\$3 or harden\$3) with (polyimide or (poly adj	US-PGPUB; EPO; JPO;	
		imide) or polymer\$2 or resin\$5) near7 (vacuum or torr or pascal or Pa or ((low\$4	DERWENT; IBM TDB	
		or below\$4 or reduc\$5) near2 pressure))) same ((pressure near5 (depend\$5 or	_	
62	2	1	USPAT;	2004/08/03 14:32
		oven or cure or cured or curing or dry\$3 or harden\$3) with (polyimide or (poly adj	US-PGPUB; EPO; JPO;	
		imide) or coat\$4 or film or layer) near7 (vacuum or torr or pascal or Pa or ((low\$4	DERWENT; IBM TDB	
		or below\$4 or reduc\$5) near2 pressure))) same ((pressure near5 (depend\$5 or	_	
		advantag\$8 or benefi\$7 or prefer\$6)))) and ((((427/163.1,163.2) or		
		(385/129,130,131,132,143)).CCLS.) ((427/350).CCLS.)		
		((427/372.2,379,385.5).CCLS.) ((528/310,322).CCLS.))		
61	102	((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3	USPAT; US-PGPUB;	2004/08/03 14:35
		or harden\$3) with (polyimide or (poly adj imide) or coat\$4 or film or layer) near7	EPO; JPO; DERWENT;	
		(vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))	IBM_TDB	
		<pre>same ((pressure near5 (depend\$5 or advantag\$8 or benefi\$7 or prefer\$6)))</pre>		
63	4294	((heat\$3 or bake or baked or baking or oven or cure or cured or curing or dry\$3	USPAT; US-PGPUB;	2004/08/03 14:36
İ		or harden\$3) with (polyimide or (poly adj imide) or coat\$4 or film or layer) near7	EPO; JPO; DERWENT;	
		<pre>(vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2 pressure)))</pre>	IBM_TDB	
64	87	same (torr or Pa or pascal or mm or mmHg) ((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 14:39
		oven or cure or cured or curing or dry\$3 or harden\$3) with (polyimide or (poly adj	US-PGPUB; EPO; JPO;	11.33
		<pre>imide)) near7 (vacuum or torr or pascal or Pa or ((low\$4 or below\$4 or reduc\$5) near2</pre>	DERWENT; IBM TDB	
		pressure))) same (torr or Pa or pascal or mm or mmHq)	-2100	

		11750		
65	41	((bake or baked or baking or cure or cured	USPAT;	2004/08/03 14:46
		or curing) near4 (polyimide or (poly adj	US-PGPUB;	1
1		imide) or polymer\$2 or resin\$4) near7	EPO; JPO;	
		(vacuum or torr or pascal or Pa or ((low\$4	DERWENT;	1
	1	or below\$4 or reduc\$5) near2 pressure)))	IBM TDB	
		with (prefer\$5 or determin\$5 or advantag\$5	_	
	Ì	or depend\$5 or optimal\$5 or benefi\$6)		
66	42	((bake or baked or baking or cure or cured	USPAT;	2004/08/03 14:44
		or curing) near4 (vacuum or torr or pascal	US-PGPUB;	
		or Pa or ((low\$4 or below\$4 or reduc\$5)	EPO; JPO;	
		near2 pressure))) with (prefer\$5 or	DERWENT;	
i		determin\$5 or advantag\$5 or depend\$5 or	IBM TDB	
		optimal\$5 or benefi\$6) near4 pressure	1201_100	
67	1	•	USPAT;	2004/08/03 14:47
"		or curing) near4 (oven or furnace) near7	US-PGPUB;	2004/00/05 14.47
		(vacuum or torr or pascal or Pa or ((low\$4	EPO; JPO;	
		or below\$4 or reduc\$5) near2 pressure)))	DERWENT;	
		with (prefer\$5 or determin\$5 or advantaq\$5		
			IBM_TDB	
		or depend\$5 or optimal\$5 or benefi\$6) near3 pressure		1
68	14	-	HODAM:	2004/00/02 14 47
00	14	((bake or baked or baking or cure or cured	USPAT;	2004/08/03 14:47
		or curing) near4 (oven or furnace) ) with	US-PGPUB;	
		(prefer\$5 or determin\$5 or advantag\$5 or	EPO; JPO;	
		depend\$5 or optimal\$5 or benefi\$6) near3	DERWENT;	
60	1	pressure	IBM_TDB	0004455455
69	386	((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 14:53
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) with (polyimide or (poly adj	EPO; JPO;	
		imide) or polymer\$2 or resin\$5) with	DERWENT;	
		((pressure near5 (depend\$5 or advantag\$8	IBM_TDB	
		or benefi\$7 or prefer\$6))))		
70	7	(,	USPAT;	2004/08/03 14:51
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) with (polyimide or (poly adj	EPO; JPO;	
		imide) ) with ((pressure near5 (depend\$5	DERWENT;	
		or advantag\$8 or benefi\$7 or prefer\$6))))	IBM TDB	
71	3	(((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 14:53
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) with (polyimide or (poly adj	EPO; JPO;	
		imide) or polymer\$2 or resin\$5) with	DERWENT;	
		((pressure near5 (depend\$5 or advantag\$8	IBM TDB	
		or benefi\$7 or prefer\$6))))) and	_	
		((((427/163.1,163.2) or		
		(385/129,130,131,132,143)).CCLS.)		
		((427/350).CCLS.)		
		((427/372.2,379,385.5).CCLS.)		
		((528/310,322).CCLS.))		
72	63	((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 14:55
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) with (polyimide or (poly adj	EPO; JPO;	
		imide) or polymer\$2 or resin\$5) near4	DERWENT;	
		(coat\$3 or film or layer or deposit\$3)	IBM TDB	
		with ((pressure near5 (depend\$5 or		
		advantag\$8 or benefi\$7 or prefer\$6))))		
73	17	((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 14:56
-	*	oven or cure or cured or curing or dry\$3	US-PGPUB;	2007/00/03 14.30
		or harden\$3) with (polyimide or (poly adj	EPO; JPO;	
		imide) or polymer\$2 or resin\$5) near4	DERWENT;	
		(coat\$3 or film or layer or deposit\$3)		
		with ((vacuum near5 (depend\$5 or	IBM_TDB	
	<u> </u>	advantag\$8 or benefi\$7 or prefer\$6))))		
74	67		HCDAM:	2004/00/02 15 00
1.3	0'	((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 15:00
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) with (polyimide or (poly adj	EPO; JPO;	
		imide) or polymer\$2 or resin\$5) near4	DERWENT;	
		(coat\$3 or film or layer or deposit\$3)	IBM_TDB	
		same ((vacuum near5 (depend\$5 or		
		advantag\$8 or benefi\$7 or prefer\$6))))		

75	1354	1 the second sec	USPAT;	2004/08/03 15:00
	-	oven or cure or cured or curing or dry\$3 or harden\$3) near3 vacuum with (polyimide	US-PGPUB;	
	Í	or (poly adj imide) or polymer\$2 or	EPO; JPO; DERWENT;	•
		resin\$5) near4 (coat\$3 or film or layer or	IBM TDB	
İ		deposit\$3) )		
76	539		USPAT;	2004/08/03 15:07
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) near3 vacuum with (polyimide	EPO; JPO;	
		or (poly adj imide) or polymer\$2 or	DERWENT;	
		resin\$5) near4 (coat\$3 or film or layer or deposit\$3) ).ti,ab.	IBM_TDB	
77	3	(((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 15:03
		oven or cure or cured or curing or dry\$3	US-PGPUB;	2004/00/03 13:03
-		or harden\$3) near3 vacuum with (polyimide	EPO; JPO;	
		or (poly adj imide) or polymer\$2 or	DERWENT;	
ļ		resin\$5) near4 (coat\$3 or film or layer or	IBM_TDB	
	-	deposit\$3) ).ti,ab.) and (degree near3 vacuum near5 (depend\$5 or determin\$5 or		
	ľ	prefer\$6 or advantage\$6 or based))		
78	26		USPAT;	2004/08/03 15:03
	İ	oven or cure or cured or curing or dry\$3	US-PGPUB;	2004/00/03 13.03
•		or harden\$3) near3 vacuum with (polyimide	EPO; JPO;	
	1	or (poly adj imide) or polymer\$2 or	DERWENT;	
		resin\$5) near4 (coat\$3 or film or layer or	IBM_TDB	
	1	deposit\$3) ).ti,ab.) and (vacuum near5 (depend\$5 or determin\$5 or prefer\$6 or		
		advantage\$6 or based))		1
79	3	(((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 15:06
		oven or cure or cured or curing or dry\$3	US-PGPUB;	2004/00/03 13:06
		or harden\$3) near3 vacuum with (polyimide	EPO; JPO;	
		or (poly adj imide) or polymer\$2 or	DERWENT;	
	]	resin\$5) near4 (coat\$3 or film or layer or	IBM_TDB	
		deposit\$3) ).ti,ab.) and		
1		((((427/163.1,163.2) or (385/129,130,131,132,143)).CCLS.)	1	
		((427/350).CCLS.)		
-		((427/372.2,379,385.5).CCLS.)		
1		((528/310,322).CCLS.))		]
80	3	(((heat\$3 or bake or baked or baking or	USPAT;	2004/08/03 15:08
		oven or cure or cured or curing or dry\$3	US-PGPUB;	
		or harden\$3) near3 vacuum with (polyimide or (poly adj imide) or polymer\$2 or	EPO; JPO;	
		resin\$5) near4 (coat\$3 or film or layer or	DERWENT;	
		deposit\$3) ).ti,ab.) and (118/\$).ccls.	IBM_TDB	
81	58	(coat\$3 or film or layer or deposit\$3)	USPAT;	2004/08/03 15:15
		with (cure or cured or curing) with vacuum	US-PGPUB;	1 1011
		near5 degree	EPO; JPO;	
1			DERWENT;	
82	12	(coat\$3 or film or layer or deposit\$3)	IBM_TDB	2004/00/00 15 15
		with (cure or cured or curing) with vacuum	USPAT; US-PGPUB;	2004/08/03 15:17
	1	near5 (depend\$4 or determin\$6 or based)	EPO; JPO;	
]			DERWENT;	
00			IBM_TDB	j i
83	175	(coat\$3 or film or layer or deposit\$3)	USPĀT;	2004/08/03 15:18
		with (cure or cured or curing) with	US-PGPUB;	
		<pre>pressure near5 (depend\$4 or determin\$6 or based)</pre>	EPO; JPO;	
		24004/	DERWENT; IBM TDB	
84	77	(coat\$3 or film or layer or deposit\$3)	USPAT;	2004/08/03 15:22
		with (cure or cured or curing) with	US-PGPUB;	= 33., 33, 03 13.22
		pressure near5 (depend\$4 or determin\$6 )	EPO; JPO;	
			DERWENT;	
85	4	(photosensi\$6 near3 (polyimide or (poly	IBM_TDB	
	4	adj imide))) and (acetophenone with	USPAT;	2004/08/03 15:32
		tertiary with (amine or amino))	US-PGPUB; EPO; JPO;	
		,,	DERWENT;	
			IBM TDB	

86	1	5426164.pn. and \$9acetophenone	USPAT;	2004/08/03 15:26
	1	3120101.pm. and 43deceophenone	US-PGPUB;	2004/00/03 13:26
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
87	1	5426164.pn. and (tertiary adj amine)	USPAT;	2004/08/03 15:26
			US-PGPUB;	
			EPO; JPO; DERWENT;	<u> </u>
	İ		IBM TDB	
88	29	(photosensi\$8 same (acetophenone with	USPAT;	2004/08/03 15:45
		tertiary with (amine or amino)))	US-PGPUB;	2001/00/03 13:43
			EPO; JPO;	
			DERWENT;	
		/WD 6100	IBM_TDB	
89	2	(HD6100 or (HD adj "6100"))	USPAT;	2004/08/03 15:30
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
90	2	(HD610045 or (HD near2 "6100"))	USPAT;	2004/08/03 15:30
			US-PGPUB;	
	,		EPO; JPO;	
			DERWENT;	
91	2	(UD6100¢E am (UD ====0 #6100#))	IBM_TDB	
) ) 1		(HD6100\$5 or (HD near2 "6100"))	USPĀT;	2004/08/03 15:30
	ĺ		US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
92	27	II   POLY	USPAT;	2004/08/03 15:50
		adj imide))) and (acetophenone and	US-PGPUB;	
		(tertiary near3 (amine or amino)))	EPO; JPO;	
	1		DERWENT;	
93	15	(photosensi\$8 same (\$8acetophenone with	IBM_TDB USPAT;	2004/08/03 16:06
		tertiary near4 (amine or amino)))	US-PGPUB;	2004/00/03 10:00
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
94	20		USPAT;	2004/08/03 15:55
		adj imide))) and ((tertiary near3 (amine or amino)) with photosensit\$7)	US-PGPUB;	
		or amino,, with photosensity,	EPO; JPO; DERWENT;	
			IBM TDB	
95	0	5694513.pn. and \$8acetophenone	USPAT;	2004/08/03 15:55
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	[
96	1040	(photosensi\$8 with (\$8acetophenone))	IBM_TDB USPAT;	2004/00/02 16 65
	1040	(vacecophenone))	USPAT; US-PGPUB;	2004/08/03 16:09
	]		EPO; JPO;	
			DERWENT;	1
	]		IBM TDB	
97	180	(photosensi\$8 with (\$8acetophenone)) and	USPAT;	2004/08/03 16:10
		polyimide	US-PGPUB;	
1			EPO; JPO;	
1			DERWENT; IBM TDB	
98	13	(photosensi\$8 with (\$8acetophenone)) same	USPAT;	2004/08/03 16:10
		polyimide	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	L		IBM TDB	